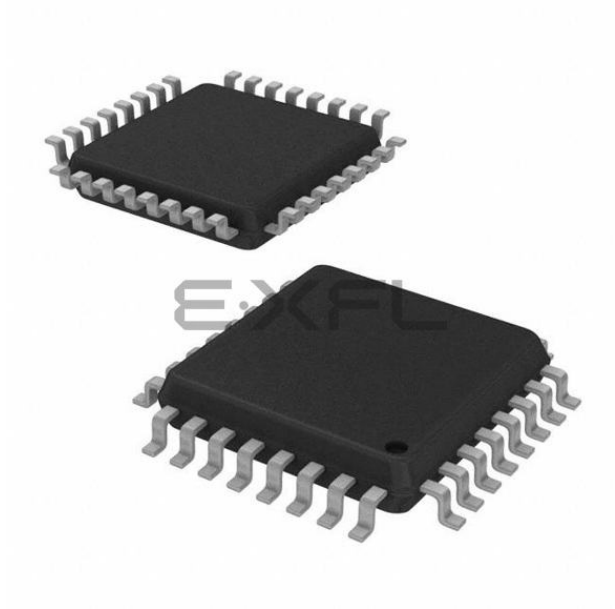

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Chapter 2
Port Integration Module (S12GPIMV1)

Chapter 31
240 KByte Flash Module (S12FTMRG240K2V1)

Appendix A
Electrical Characteristics

Table 1-18. 48-Pin LQFP Pinout for S12GA48 and S12GA64

	Function <----lowest-----PRIORITY-----highest---->					Power Supply	Internal Pull Resistor	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func		CTRL	Reset State
30	PAD10	KWAD10	AN10	ACMPP		V_{DDA}	PER0AD/PPS0AD	Disabled
31	PAD3	KWAD3	AN3	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
32	PAD11	KWAD11	AN11	ACMPM		V_{DDA}	PER0AD/PPS0AD	Disabled
33	PAD4	KWAD4	AN4	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
34	PAD5	KWAD5	AN5	—	—	V_{DDA}	PER1AD/PPS0AD	Disabled
35	PAD6	KWAD6	AN6	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
36	PAD7	KWAD7	AN7	—	—	V_{DDA}	PER1AD/PPS1AD	Disabled
37	VDDA	VRH	—	—	—	—	—	—
38	VSSA	—	—	—	—	—	—	—
39	PS0	RXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
40	PS1	TXD0	—	—	—	V_{DDX}	PERS/PPSS	Up
41	PS2	RXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
42	PS3	TXD1	—	—	—	V_{DDX}	PERS/PPSS	Up
43	PS4	MISO0	—	—	—	V_{DDX}	PERS/PPSS	Up
44	PS5	MOSI0	—	—	—	V_{DDX}	PERS/PPSS	Up
45	PS6	SCK0	—	—	—	V_{DDX}	PERS/PPSS	Up
46	PS7	API_EXTCLK	ECLK	$\overline{SS0}$	—	V_{DDX}	PERS/PPSS	Up
47	PM0	RXCAN	—	—	—	V_{DDX}	PERM/PPSM	Disabled
48	PM1	TXCAN	—	—	—	V_{DDX}	PERM/PPSM	Disabled

[1] The regular I/O characteristics (see Section A.2, “I/O Characteristics”) apply if the EXTAL/XTAL function is disabled

Table 2-32. PUCR Register Field Descriptions (continued)

Field	Description
2 PUPCE	**Port C Pullup Enable**—Enable pullup devices on all port input pins This bit configures whether a pullup device is activated on all associated port input pins. If a pin is used as output this bit has no effect. 1 Pullup devices enabled 0 Pullup devices disabled
1 PUPBE	**Port B Pullup Enable**—Enable pullup devices on all port input pins This bit configures whether a pullup device is activated on all associated port input pins. If a pin is used as output this bit has no effect. 1 Pullup devices enabled 0 Pullup devices disabled
0 PUPAE	**Port A Pullup Enable**—Enable pullup devices on all port input pins This bit configures whether a pullup device is activated on all associated port input pins. If a pin is used as output this bit has no effect. 1 Pullup devices enabled 0 Pullup devices disabled

Table 2-61. PTP Register Field Descriptions

Field	Description
7-0 PTP	**Port P general-purpose input/output data**—Data Register When not used with an alternative signal, the associated pin can be used as general-purpose I/O. In general-purpose output mode the port data register bit value is driven to the pin. If the associated data direction bit is set to 1, a read returns the value of the port data register bit, otherwise the buffered pin input state is read.

2.4.3.35 Port P Input Register (PTIP)

Address 0x0259 (G1, G2) Access: User read only[1]

	7	6	5	4	3	2	1	0
R	PTIP7	PTIP6	PTIP5	PTIP4	PTIP3	PTIP2	PTIP1	PTIP0
W								
Reset	0	0	0	0	0	0	0	0

Address 0x0259 (G3) Access: User read only[1]

	7	6	5	4	3	2	1	0
R	0	0	PTIP5	PTIP4	PTIP3	PTIP2	PTIP1	PTIP0
W								
Reset	0	0	0	0	0	0	0	0

Figure 2-36. Port P Input Register (PTIP)

[1] Read: Anytime
Write:Never

Table 2-62. PTIP Register Field Descriptions

Field	Description
7-0 PTIP	**Port P input data**— A read always returns the buffered input state of the associated pin. It can be used to detect overload or short circuit conditions on output pins.

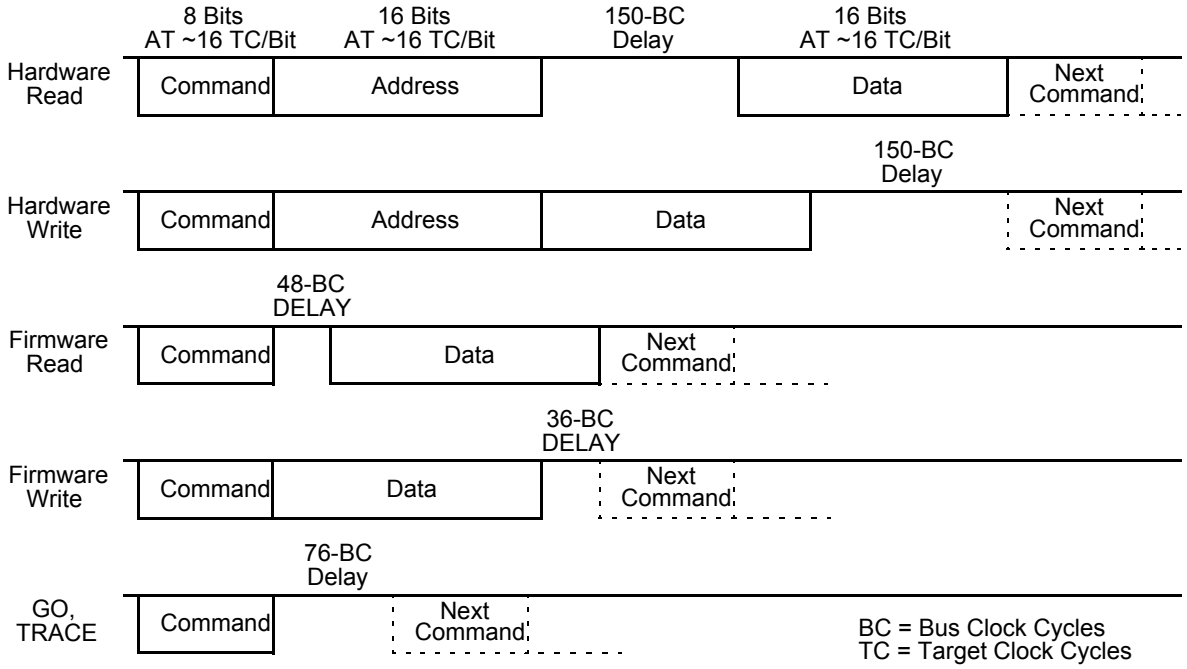

Figure 7-6. BDM Command Structure

7.4.6 BDM Serial Interface

The BDM communicates with external devices serially via the BKGD pin. During reset, this pin is a mode select input which selects between normal and special modes of operation. After reset, this pin becomes the dedicated serial interface pin for the BDM.

The BDM serial interface is timed based on the VCO clock (please refer to the CPMU Block Guide for more details), which gets divided by 8. This clock will be referred to as the target clock in the following explanation.

The BDM serial interface uses a clocking scheme in which the external host generates a falling edge on the BKGD pin to indicate the start of each bit time. This falling edge is sent for every bit whether data is transmitted or received. Data is transferred most significant bit (MSB) first at 16 target clock cycles per bit. The interface times out if 512 clock cycles occur between falling edges from the host.

The BKGD pin is a pseudo open-drain pin and has an weak on-chip active pull-up that is enabled at all times. It is assumed that there is an external pull-up and that drivers connected to BKGD do not typically drive the high level. Since R-C rise time could be unacceptably long, the target system and host provide brief driven-high (speedup) pulses to drive BKGD to a logic 1. The source of this speedup pulse is the host for transmit cases and the target for receive cases.

The timing for host-to-target is shown in Figure 7-7 and that of target-to-host in Figure 7-8 and Figure 7-9. All four cases begin when the host drives the BKGD pin low to generate a falling edge. Since the host and target are operating from separate clocks, it can take the target system up to one full clock cycle to recognize this edge. The target measures delays from this perceived start of the bit time while the host measures delays from the point it actually drove BKGD low to start the bit up to one target clock cycle

- Autonomous periodical interrupt (API)
- Bus Clock Generator
  - Clock switch to select either PLLCLK or external crystal/resonator based Bus Clock
  - PLLCLK divider to adjust system speed
- System Reset generation from the following possible sources:
  - Power-on reset (POR)
  - Low-voltage reset (LVR)
  - Illegal address access
  - COP time out
  - Loss of oscillation (clock monitor fail)
  - External pin $\overline{\text{RESET}}$

10.1.2 Modes of Operation

This subsection lists and briefly describes all operating modes supported by the S12CPMU.

10.1.2.1 Run Mode

The voltage regulator is in Full Performance Mode (FPM).

The Phase Locked Loop (PLL) is on.

The Internal Reference Clock (IRC1M) is on.

The API is available.

- PLL Engaged Internal (PEI)
  - This is the default mode after System Reset and Power-On Reset.
  - The Bus Clock is based on the PLLCLK.
  - After reset the PLL is configured for 50 MHz VCOCLK operation
    Post divider is 0x03, so PLLCLK is VCOCLK divided by 4, that is 12.5MHz and Bus Clock is 6.25MHz.
    The PLL can be re-configured for other bus frequencies.
  - The reference clock for the PLL (REFCLK) is based on internal reference clock IRC1M
- PLL Engaged External (PEE)
  - The Bus Clock is based n the PLLCLK.
  - This mode can be entered from default mode PEI by performing the following steps:
    - Configure the PLL for desired bus frequency.
    - Program the reference divider (REFDIV[3:0] bits) to divide down oscillator frequency if necessary.
    - Enable the external oscillator (OSCE bit)
    - Wait for oscillator to start up (UPOSC=1) and PLL to lock (LOCK=1).
- PLL Bypassed External (PBE)

11.3.2.9 ATD Status Register 2 (ATDSTAT2)

This read-only register contains the Conversion Complete Flags CCF[7:0].

Module Base + 0x000A

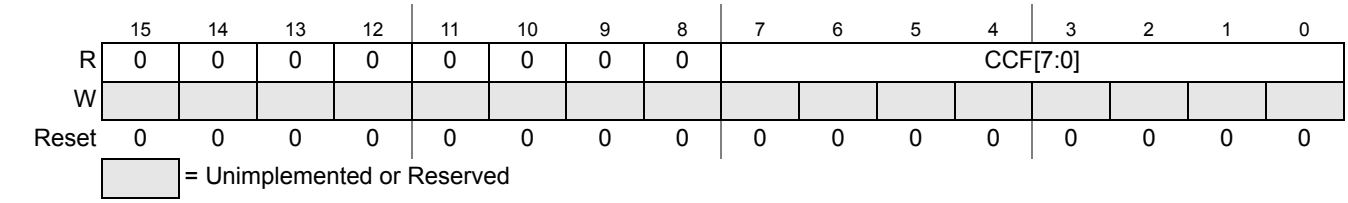

Figure 11-11. ATD Status Register 2 (ATDSTAT2)

Read: Anytime

Write: Anytime (for details see Table 11-18 below)

Table 11-18. ATDSTAT2 Field Descriptions

Field	Description
7–0 CCF[7:0]	**Conversion Complete Flag *n* (*n*= 7, 6, 5, 4, 3, 2, 1, 0) (*n conversion number, NOT channel number!)*—** A conversion complete flag is set at the end of each conversion in a sequence. The flags are associated with the conversion position in a sequence (and also the result register number). Therefore in non-fifo mode, CCF[4] is set when the fifth conversion in a sequence is complete and the result is available in result register ATDDR4; CCF[5] is set when the sixth conversion in a sequence is complete and the result is available in ATDDR5, and so forth. If automatic compare of conversion results is enabled (CMPE[*n*]=1 in ATDCMPE), the conversion complete flag is only set if comparison with ATDDR*n* is true. If ACMPIE=1 a compare interrupt will be requested. In this case, as the ATDDR*n* result register is used to hold the compare value, the result will not be stored there at the end of the conversion but is lost. A flag CCF[*n*] is cleared when one of the following occurs: A) Write to ATDCTL5 (a new conversion sequence is started) B) If AFFC=0, write “1” to CCF[*n*] C) If AFFC=1 and CMPE[*n*]=0, read of result register ATDDR*n* D) If AFFC=1 and CMPE[*n*]=1, write to result register ATDDR*n* In case of a concurrent set and clear on CCF[*n*]: The clearing by method A) will overwrite the set. The clearing by methods B) or C) or D) will be overwritten by the set. 0 Conversion number *n* not completed or successfully compared 1 If (CMPE[*n*]=0): Conversion number *n* has completed. Result is ready in ATDDR*n*. If (CMPE[*n*]=1): Compare for conversion result number *n* with compare value in ATDDR*n*, using compare operator CMPGT[*n*] is true. (No result available in ATDDR*n*)

14.3.2.12.2 Right Justified Result Data (DJM=1)

Module Base +
0x0010 = ATDDR0, 0x0012 = ATDDR1, 0x0014 = ATDDR2, 0x0016 = ATDDR3
0x0018 = ATDDR4, 0x001A = ATDDR5, 0x001C = ATDDR6, 0x001E = ATDDR7
0x0020 = ATDDR8, 0x0022 = ATDDR9, 0x0024 = ATDDR10, 0x0026 = ATDDR11

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
R	0	0	0	0	Result-Bit[11:0]											
W																
Reset	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 14-15. Right justified ATD conversion result register (ATDDR*n*)

Table 14-22 shows how depending on the A/D resolution the conversion result is transferred to the ATD result registers for right justified data. Compare is always done using all 12 bits of both the conversion result and the compare value in ATDDRn.

Table 14-22. Conversion result mapping to ATDDRn

A/D resolution	DJM	conversion result mapping to ATDDR*n*
8-bit data	1	Result-Bit[11:8]=0000, Result-Bit[7:0] = conversion result
10-bit data	1	Result-Bit[11:10]=00, Result-Bit[9:0] = conversion result
12-bit data	1	Result-Bit[11:0] = result

Module Base + 0x0001 Access: User read/write[1]

	7	6	5	4	3	2	1	0
R	CANE	CLKSRC	LOOPB	LISTEN	BORM	WUPM	SLPAK	INITAK
W								
Reset:	0	0	0	1	0	0	0	1

= Unimplemented

Figure 18-5. MSCAN Control Register 1 (CANCTL1)

[1] Read: Anytime
Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1), except CANE which is write once in normal and anytime in special system operation modes when the MSCAN is in initialization mode (INITRQ = 1 and INITAK = 1)

Table 18-4. CANCTL1 Register Field Descriptions

Field	Description
7 CANE	**MSCAN Enable** 0 MSCAN module is disabled 1 MSCAN module is enabled
6 CLKSRC	**MSCAN Clock Source** — This bit defines the clock source for the MSCAN module (only for systems with a clock generation module; Section 18.4.3.2, “Clock System,” and Section Figure 18-43., “MSCAN Clocking Scheme,”). 0 MSCAN clock source is the oscillator clock 1 MSCAN clock source is the bus clock
5 LOOPB	**Loopback Self Test Mode** — When this bit is set, the MSCAN performs an internal loopback which can be used for self test operation. The bit stream output of the transmitter is fed back to the receiver internally. The RXCAN input is ignored and the TXCAN output goes to the recessive state (logic 1). The MSCAN behaves as it does normally when transmitting and treats its own transmitted message as a message received from a remote node. In this state, the MSCAN ignores the bit sent during the ACK slot in the CAN frame acknowledge field to ensure proper reception of its own message. Both transmit and receive interrupts are generated. 0 Loopback self test disabled 1 Loopback self test enabled
4 LISTEN	**Listen Only Mode** — This bit configures the MSCAN as a CAN bus monitor. When LISTEN is set, all valid CAN messages with matching ID are received, but no acknowledgement or error frames are sent out (see Section 18.4.4.4, “Listen-Only Mode”). In addition, the error counters are frozen. Listen only mode supports applications which require “hot plugging” or throughput analysis. The MSCAN is unable to transmit any messages when listen only mode is active. 0 Normal operation 1 Listen only mode activated
3 BORM	**Bus-Off Recovery Mode** — This bit configures the bus-off state recovery mode of the MSCAN. Refer to Section 18.5.2, “Bus-Off Recovery,” for details. 0 Automatic bus-off recovery (see Bosch CAN 2.0A/B protocol specification) 1 Bus-off recovery upon user request
2 WUPM	**Wake-Up Mode** — If WUPE in CANCTL0 is enabled, this bit defines whether the integrated low-pass filter is applied to protect the MSCAN from spurious wake-up (see Section 18.4.5.5, “MSCAN Sleep Mode”). 0 MSCAN wakes up on any dominant level on the CAN bus 1 MSCAN wakes up only in case of a dominant pulse on the CAN bus that has a length of T_{wup}

18.3.2.17 MSCAN Identifier Acceptance Registers (CANIDAR0-7)

On reception, each message is written into the background receive buffer. The CPU is only signalled to read the message if it passes the criteria in the identifier acceptance and identifier mask registers (accepted); otherwise, the message is overwritten by the next message (dropped).

The acceptance registers of the MSCAN are applied on the IDR0–IDR3 registers (see Section 18.3.3.1, “Identifier Registers (IDR0–IDR3)”) of incoming messages in a bit by bit manner (see Section 18.4.3, “Identifier Acceptance Filter”).

For extended identifiers, all four acceptance and mask registers are applied. For standard identifiers, only the first two (CANIDAR0/1, CANIDMR0/1) are applied.

Module Base + 0x0010 to Module Base + 0x0013 Access: User read/write[1]

	7	6	5	4	3	2	1	0
R W	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
Reset	0	0	0	0	0	0	0	0

Figure 18-20. MSCAN Identifier Acceptance Registers (First Bank) — CANIDAR0–CANIDAR3

1 Read: Anytime
Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1)

Table 18-22. CANIDAR0–CANIDAR3 Register Field Descriptions

Field	Description
7-0 AC[7:0]	**Acceptance Code Bits** — AC[7:0] comprise a user-defined sequence of bits with which the corresponding bits of the related identifier register (IDRn) of the receive message buffer are compared. The result of this comparison is then masked with the corresponding identifier mask register.

Module Base + 0x0018 to Module Base + 0x001B Access: User read/write[1]

	7	6	5	4	3	2	1	0
R W	AC7	AC6	AC5	AC4	AC3	AC2	AC1	AC0
Reset	0	0	0	0	0	0	0	0

Figure 18-21. MSCAN Identifier Acceptance Registers (Second Bank) — CANIDAR4–CANIDAR7

1 Read: Anytime
Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1)

- For channels 0, 1, 4, and 5 the clock choices are clock A.
- For channels 2, 3, 6, and 7 the clock choices are clock B.

19.6 Interrupts

The PWM module has no interrupt.

25.3.2.9.1 P-Flash Protection Restrictions

The general guideline is that P-Flash protection can only be added and not removed. Table 25-21 specifies all valid transitions between P-Flash protection scenarios. Any attempt to write an invalid scenario to the FPROT register will be ignored. The contents of the FPROT register reflect the active protection scenario. See the FPHS and FPLS bit descriptions for additional restrictions.

Table 25-21. P-Flash Protection Scenario Transitions

From Protection Scenario	To Protection Scenario[1]							
	0	1	2	3	4	5	6	7
0	X	X	X	X				
1		X		X				
2			X	X				
3				X				
4				X	X			
5			X	X	X	X		
6		X		X	X		X	
7	X	X	X	X	X	X	X	X

1 Allowed transitions marked with X, see Figure 25-14 for a definition of the scenarios.

25.3.2.10 EEPROM Protection Register (EEPROT)

The EEPROT register defines which EEPROM sectors are protected against program and erase operations.

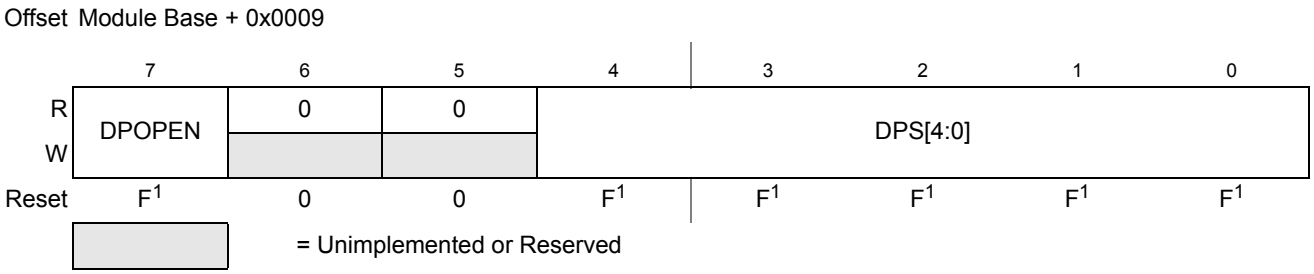

Figure 25-15. EEPROM Protection Register (EEPROT)

1 Loaded from IFR Flash configuration field, during reset sequence.

The (unreserved) bits of the EEPROT register are writable with the restriction that protection can be added but not removed. Writes must increase the DPS value and the DPOPEN bit can only be written from 1 (protection disabled) to 0 (protection enabled). If the DPOPEN bit is set, the state of the DPS bits is irrelevant.

user-supplied keys match those stored in the Flash security bytes of the Flash configuration field (see Table 25-4). The Verify Backdoor Access Key command must not be executed from the Flash block containing the backdoor comparison key to avoid code runaway.

Table 25-52. Verify Backdoor Access Key Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters	
000	0x0C	Not required
001	Key 0	
010	Key 1	
011	Key 2	
100	Key 3	

Upon clearing CCIF to launch the Verify Backdoor Access Key command, the Memory Controller will check the FSEC KEYEN bits to verify that this command is enabled. If not enabled, the Memory Controller sets the ACCERR bit in the FSTAT register and terminates. If the command is enabled, the Memory Controller compares the key provided in FCCOB to the backdoor comparison key in the Flash configuration field with Key 0 compared to 0x3_FF00, etc. If the backdoor keys match, security will be released. If the backdoor keys do not match, security is not released and all future attempts to execute the Verify Backdoor Access Key command are aborted (set ACCERR) until a reset occurs. The CCIF flag is set after the Verify Backdoor Access Key operation has completed.

Table 25-53. Verify Backdoor Access Key Command Error Handling

Register	Error Bit	Error Condition
FSTAT	ACCERR	Set if CCOBIX[2:0] != 100 at command launch
		Set if an incorrect backdoor key is supplied
		Set if backdoor key access has not been enabled (KEYEN[1:0] != 10, see Section 25.3.2.2)
		Set if the backdoor key has mismatched since the last reset
	FPVIOL	None
	MGSTAT1	None
	MGSTAT0	None

25.4.6.12 Set User Margin Level Command

The Set User Margin Level command causes the Memory Controller to set the margin level for future read operations of the P-Flash or EEPROM block.

Table 25-54. Set User Margin Level Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters	
000	0x0D	Flash block selection code [1:0]. See Table 25-34

Table 30-15. FSTAT Field Descriptions (continued)

Field	Description
3 MGBUSY	**Memory Controller Busy Flag** — The MGBUSY flag reflects the active state of the Memory Controller. 0 Memory Controller is idle 1 Memory Controller is busy executing a Flash command (CCIF = 0)
2 RSVD	**Reserved Bit** — This bit is reserved and always reads 0.
1–0 MGSTAT[1:0]	**Memory Controller Command Completion Status Flag** — One or more MGSTAT flag bits are set if an error is detected during execution of a Flash command or during the Flash reset sequence. See Section 30.4.6, “Flash Command Description,” and Section 30.6, “Initialization” for details.

30.3.2.8 Flash Error Status Register (FERSTAT)

The FERSTAT register reflects the error status of internal Flash operations.

Offset Module Base + 0x0007

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	DFDIF	SFDIF
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 30-12. Flash Error Status Register (FERSTAT)

All flags in the FERSTAT register are readable and only writable to clear the flag.

Table 30-16. FERSTAT Field Descriptions

Field	Description
1 DFDIF	**Double Bit Fault Detect Interrupt Flag** — The setting of the DFDIF flag indicates that a double bit fault was detected in the stored parity and data bits during a Flash array read operation or that a Flash array read operation returning invalid data was attempted on a Flash block that was under a Flash command operation.[1] The DFDIF flag is cleared by writing a 1 to DFDIF. Writing a 0 to DFDIF has no effect on DFDIF.[2] 0 No double bit fault detected 1 Double bit fault detected or a Flash array read operation returning invalid data was attempted while command running
0 SFDIF	**Single Bit Fault Detect Interrupt Flag** — With the IGNSF bit in the FCNFG register clear, the SFDIF flag indicates that a single bit fault was detected in the stored parity and data bits during a Flash array read operation or that a Flash array read operation returning invalid data was attempted on a Flash block that was under a Flash command operation.[1] The SFDIF flag is cleared by writing a 1 to SFDIF. Writing a 0 to SFDIF has no effect on SFDIF. 0 No single bit fault detected 1 Single bit fault detected and corrected or a Flash array read operation returning invalid data was attempted while command running

1 The single bit fault and double bit fault flags are mutually exclusive for parity errors (an ECC fault occurrence can be either single fault or double fault but never both). A simultaneous access collision (Flash array read operation returning invalid data attempted while command running) is indicated when both SFDIF and DFDIF flags are high.

2 There is a one cycle delay in storing the ECC DFDIF and SFDIF fault flags in this register. At least one NOP is required after a flash memory read before checking FERSTAT for the occurrence of ECC errors.

Table 31-3. P-Flash Memory Addressing

Global Address	Size (Bytes)	Description
0x0_4000 – 0x3_FFFF	240 K	P-Flash Block Contains Flash Configuration Field (see Table 31-4).

The FPROT register, described in Section 31.3.2.9, can be set to protect regions in the Flash memory from accidental program or erase. The Flash memory addresses covered by these protectable regions are shown in the P-Flash memory map. The higher address region is mainly targeted to hold the boot loader code since it covers the vector space. Default protection settings as well as security information that allows the MCU to restrict access to the Flash module are stored in the Flash configuration field as described in Table 31-4.

Table 31-4. Flash Configuration Field

Global Address	Size (Bytes)	Description
0x3_FF00-0x3_FF07	8	Backdoor Comparison Key Refer to Section 31.4.6.11, “Verify Backdoor Access Key Command,” and Section 31.5.1, “Unsecuring the MCU using Backdoor Key Access”
0x3_FF08-0x3_FF0B[1]	4	Reserved
0x3_FF0C[1]	1	P-Flash Protection byte. Refer to Section 31.3.2.9, “P-Flash Protection Register (FPROT)”
0x3_FF0D[1]	1	EEPROM Protection byte. Refer to Section 31.3.2.10, “EEPROM Protection Register (EEPROT)”
0x3_FF0E[1]	1	Flash Nonvolatile byte Refer to Section 31.3.2.16, “Flash Option Register (FOPT)”
0x3_FF0F[1]	1	Flash Security byte Refer to Section 31.3.2.2, “Flash Security Register (FSEC)”

1 0x3FF08-0x3_FF0F form a Flash phrase and must be programmed in a single command write sequence. Each byte in the 0x3_FF08 - 0x3_FF0B reserved field should be programmed to 0xFF.

31.4.4.3 Valid Flash Module Commands

Table 31-27 present the valid Flash commands, as enabled by the combination of the functional MCU mode (Normal SingleChip NS, Special Singlechip SS) with the MCU security state (Unsecured, Secured).

Special Singlechip mode is selected by input mmc_ss_mode_ts2 asserted. MCU Secured state is selected by input mmc_secure input asserted.

Table 31-27. Flash Commands by Mode and Security State

FCMD	Command	Unsecured		Secured	
		NS[1]	SS[2]	NS[3]	SS[4]
0x01	Erase Verify All Blocks	*	*	*	*
0x02	Erase Verify Block	*	*	*	*
0x03	Erase Verify P-Flash Section	*	*	*	
0x04	Read Once	*	*	*	
0x06	Program P-Flash	*	*	*	
0x07	Program Once	*	*	*	
0x08	Erase All Blocks		*		*
0x09	Erase Flash Block	*	*	*	
0x0A	Erase P-Flash Sector	*	*	*	
0x0B	Unsecure Flash		*		*
0x0C	Verify Backdoor Access Key	*		*	
0x0D	Set User Margin Level	*	*	*	
0x0E	Set Field Margin Level		*		
0x10	Erase Verify EEPROM Section	*	*	*	
0x11	Program EEPROM	*	*	*	
0x12	Erase EEPROM Sector	*	*	*	

1 Unsecured Normal Single Chip mode
2 Unsecured Special Single Chip mode.
3 Secured Normal Single Chip mode.
4 Secured Special Single Chip mode.

31.4.4.4 P-Flash Commands

Table 31-28 summarizes the valid P-Flash commands along with the effects of the commands on the P-Flash block and other resources within the Flash module.

Table 31-28. P-Flash Commands

FCMD	Command	Function on P-Flash Memory
0x01	Erase Verify All Blocks	Verify that all P-Flash (and EEPROM) blocks are erased.

Version Number	Revision Date	Description of Changes
Rev 0.49	5-Jun-2013	• Updated Section A.1.1, “Parameter Classification” • Applied new M-parameter tag in Table A-7, Table A-9, Table A-11, Table A-16, Table A-22, Table A-24, Table A-26, Table A-28, Table A-32, Table A-43, Table A-45, and Table A-48 • Updated Table A-39 (Num 2b, 6b)
Rev 0.50	15-Jul-2013	• Updated Section A.7, “NVM” (format and timing parameters)
Rev 0.51	23-Oct-2017	• Updated mask set condition in Table A-44 (Num 7a, 7b, 8a, 8b) • Updated mask set condition in Table A-45 (Num 7a, 7b, 8a, 8b)

A.1 General

This supplement contains the most accurate electrical information for the MC9S12G microcontroller available at the time of publication.

This introduction is intended to give an overview on several common topics like power supply, current injection etc.

A.1.1 Parameter Classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give the customer a better understanding the following classification is used and the parameters are tagged accordingly in the tables where appropriate.

NOTE

This classification is shown in the column labeled “C” in the parameter tables where appropriate.

P: Those parameters are guaranteed during production testing on each individual device.

M: These parameters are characterized at 160°C and tested in production at an ambient temperature of 150°C with appropriate guardbanding to guarantee operation at 160°C.

C: Those parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations.

T: Those parameters are achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted. All values shown in the typical column are within this category.

D: Those parameters are derived mainly from simulations.

A.1.2 Power Supply

The VDDA, VSSA pin pairs supply the A/D converter and parts of the internal voltage regulator.

The VDDX, VSSX pin pairs [3:1] supply the I/O pins.

VDDR supplies the internal voltage regulator.

The VDDF, VSS1 pin pair supplies the internal NVM logic.

Table A-33. Static Electrical Characteristics

Characteristics noted under conditions 3.13V <= VDDA <= 5.5V>, -40°C < Tj < 150°C >, VRH=VDDA, VRL=VSSA unless otherwise noted. Typical values noted reflect the approximate parameter mean at T_A = 25°C under nominal conditions unless otherwise noted.							
Num	**C**	**Ratings**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
8	C	Output Voltage unbuffered range A or B (load >= 50MΩ)	V_{out}	full DAC Range A or B			V
9	P	Output Voltage (DRIVE bit = 0)[1] buffered range A (load >= 100KΩ to VSSA) buffered range A (load >= 100KΩ to VDDA) buffered range B (load >= 100KΩ to VSSA) buffered range B (load >= 100KΩ to VDDA)	V_{out}	0 0.15 full DAC Range B	- - 	VDDA-0.15 VDDA 	V
10	P	Output Voltage (DRIVE bit = 1)[2] buffered range B with 6.4KΩ load into resistor divider of 800Ω /6.56KΩ between VDDA and VSSA. (equivalent load is >= 65KΩ to VSSA) or (equivalent load is >= 7.5KΩ to VDDA)	V_{out}	full DAC Range B			V
11	D	Buffer Output Capacitive load	C_{load}	0	-	100	pF
12	P	Buffer Output Offset	V_{offset}	-30	-	+30	mV
13	P	Settling time	t_{delay}	-	3	5	µs
14	D	Reverence voltage high	V_{refh}	VDDA-0.1V	VDDA	VDDA+0.1V	V

1 DRIVE bit = 1 is not recommended in this case.

2 DRIVE bit = 0 is not allowed with this high load.

A.7 NVM

A.7.1 Timing Parameters

The time base for all NVM program or erase operations is derived from the bus clock using the FCLKDIV register. The frequency of this derived clock must be set within the limits specified as f_{NVMOP}. The NVM module does not have any means to monitor the frequency and will not prevent program or erase operation at frequencies above or below the specified minimum. When attempting to program or erase the NVM module at a lower frequency, a full program or erase transition is not assured.

All timing parameters are a function of the bus clock frequency, fNVMBUS. All program and erase times are also a function of the NVM operating frequency, f_{NVMOP}.

NOTE

The LVR monitors the voltages V_{DD}, V_{DDF} and V_{DDX}. As soon as voltage drops on these supplies which would prohibit the correct function of the microcontroller, the LVR is triggering a reset.

A.13 Chip Power-up and Voltage Drops

LVI (low voltage interrupt), POR (power-on reset) and LVRs (low voltage reset) handle chip power-up or drops of the supply voltage.

Figure A-6. Chip Power-up and Voltage Drops